

SIDDHARTH GROUP OF INSTITUTIONS :: PUTTUR (AUTONOMOUS)

Siddharth Nagar, Narayanavanam Road - 517583

QUESTION BANK (DESCRIPTIVE)

Subject with Code : Electronic Devices (18EC0401)

Course & Branch: B.Tech - ECE

Year & Sem: II-B.Tech & I-Sem

Regulation: R18

<u>UNIT –I</u>

PN JUNCTION DIODE

[L1][CO1][2M]
[L1][CO1][2M]
[L2][CO1][2M]
[L1][CO1][2M]
[L2][CO1][2M]
[L2][CO1][2M]
[L3][CO1][2M]
[L1][C01][2M]
[L1][C01][2M]
[L1][C01][2M]
[L2][CO1][5M]
[L2][C01][5M]
vits V-I
[L2][CO1][10M]
[L2][C01][10M]
ssion for
[L2][CO1][10M]
[L1][C01][5M]
[L2][C01][5M]
[L1][C01][2M]
[L3][C01][8M]
[L1][C01][2M]
[L3][CO1][8M]
[L1][C01][7M]
10µA,
[L3][CO1][3M]
[L2][CO1][5M]
[L3][CO1][5M]
[L2][C01][10M]
e
[L1][CO1][5M]
[L1][CO1][5M]

<u>UNIT –II</u>

RECTIFIERS, FILTERS AND SPECIAL PURPOSE DEVICES

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1. Two Mark Questions:	
1. What is rectifier?	[L1][CO2][2M]
2. Compare Half wave rectifier and Full wave rectifier.	[L2][CO2][2M]
3. Define Peak Inverse Voltage of Half Wave Rectifier.	[L1][CO2][2M]
4. What are the disadvantages of Half wave rectifier?	[L2][CO2][2M]
5. Mention the advantages of Full Wave Rectifier.	[L1][CO2][2M]
6. Write down the need for filters in power supplies.	[L2][CO2][2M]
7. Calculate the ripple factor of a LC filter with FWR for a inductance of 10H and	
capacitance of 8μ for 50Hz AC input supply.	[L3][CO2][2M]
8. What are the applications of Zener Diode?	[L1][CO2][2M]
9. Mention the applications of Varactor Diode.	[L1][CO2][2M]
10. Define Tunneling.	[L1][CO2][2M]
II. Part – B Questions:	
1. a) Draw the circuit diagram of half wave rectifier and explain its operation with the he	2lp
Of waveforms.	[L2][CO2][5M]
b) Derive the expressions for Ripple Factor and Efficiency of Half Wave Rectifier.	[L1][CO2][5M]
2. Derive the expressions for Average DC current, Average DC Voltage, RMS Value	of
Current, DC Power Output and AC Power Input of a Half Wave Rectifier.	[L1][CO2][10M]
3. a) Draw the circuit diagram of Full wave rectifier and explain its operation with the he	elp
Of waveforms.	[L2][CO2][5M]
b) Derive the expressions for Ripple Factor and Efficiency of Full Wave Rectifier.	[L1][CO2][5M]
4. Derive the expressions for Average DC current, Average DC Voltage, RMS Value	of
Current, DC Power Output and AC Power Input of a Full Wave Rectifier.	[L1][CO2][10M]
5. A Half wave rectifier has a load of $3.5k\Omega$. If the diode resistance and the secondary	coil
Resistance together have resistance of 800Ω and the input voltage of 240V, Calculated	te
(i) Peak, Average and RMS value of the current flowing, (ii) DC power output, (iii)	AC
Power input and (iv) efficiency of the rectifier.	[L1][CO2][10M]
6. a) With neat diagram, explain Bridge Rectifier.	[L2][CO2][5M]
b) Compare the different types of filter circuits in terms of ripple factors.	[L4][CO2][5M]
7. a) Explain the working of capacitor filter and derive the expression for ripple factor of	
Capacitor filter.	[L3][CO2][5M]
b) Derive the expression for ripple factor of inductor filter.	[L3][CO2][5M]
8. a) Derive the Ripple Factor For L Section Filter.	[L1][CO2][5M]
b) Derive the expression for Ripple Factor of CLC Filter.	[L1][CO2][5M]
9. a) Draw and discuss the VI characteristics of a Zener Diode.	[L2][CO2][5M]
b) Discuss about Varactor diode.	[L1][CO2][5M]
10. a) Draw and describe VI characteristics of Tunnel Diode.	[L2][CO2][5M]
b) Describe the characteristics and applications of a photodiode.	[L1][CO2][5M]
11. a) Explain the construction and applications of Solar Cell.	[L2][CO2][5M]
b) Draw and explain the basic structure of LED. Mention the applications of LED.	[L2][CO2][5M]

<u>UNIT –III</u>

BIPOLAR JUNCTION TRANSISTOR

I.	Two Mark Questions:	
1	. What are the different configurations of BJT?	[L1][CO3][2M]
2	. Mention the applications of Transistor.	[L2][CO3][2M]
3	, What do you mean by Punch Through Effect?	[L1][CO3][2M]
4	. Mention the three regions of operation of BJT.	[L1][CO3][2M]
5	. In Common Base connection, the emitter current is 6.28mA and the collector	
	Current is 6.20mA. Determine common base current gain.	[L3][CO3][2M]
6	. If a transistor has $\alpha = 0.97$, find the value of β .	[L3][CO3][2M]
7	. Define Q Point of BJT.	[L1][CO3][2M]
8	. What is stability factor?	[L1][CO3][2M]
9	. Mention the disadvantages of fixed bias circuit of BJT.	[L1][CO3][2M]
1	0. What is thermal runaway? How can it be avoided?	[L2][CO3][2M]
I	I. Part – B Ouestions:	
1.	a) Discuss the operation of NPN transistor with diagram.	[L2][CO3][5M]
	b) If the base current in a transistor is 20µA when the emitter current is 6.4mA, what	
	are the values of α and β ? Also calculate the collector current.	[L3][CO3][5M]
2.	a) What is early effect of a BJT?	[L1][CO3][2M]
	b) With neat diagram, explain the Input and Output characteristics of a BJT in CB	
	Configuration.	[L2][CO3][8M]
3.	Discuss the Input and Output characteristics of a BJT in CE Configuration. Indicate the	e regions
	of operations in the output characteristics.	[L2][CO3][10M]
4.	a) Describe the Input and Output characteristics of BJT in CC Configuration.	[L2][CO3][5M]
	b) Write notes on Breakdown in transistors.	[L1][CO3][5M]
5.	a) Define Transistor Biasing and explain the need for Biasing?	[L1][CO3][5M]
	b) Explain the concept of DC and AC Load lines and discuss the criteria for fixing the	
	Q-point.	[L2][CO3][5M]
6.	a) Mention different types of Biasing a Transistor and explain the Fixed Bias of a	
	Transistor	[L2][CO3][5M]
	b) Explain Collector to Base bias of a Transistor with neat circuit diagram	[L2][CO3][5M]
7.	Derive the stability factors S, S' and S'' of a Transistor Voltage Divider bias.	[L3][CO3][10M]
8.	a) For the circuit shown in the Figure, calculate I_B , I_C , V_{CE} , V_B , V_C and V_{BC} . Assume t	hat
	$V_{BE} = 0$ and $\beta = 50$.	[L3][CO3][5M]
	V _{CC} + 10 V	



- b) Discuss Diode Compensation Technique for the parameters V_{BE} and I_{CO} .
- 9. a) Describe Thermistor and Sensistor Compensation Techniques.
 - b) Discuss about Thermal Runaway and Thermal Resistance.
- 10. Derive the condition for Thermal Stability to avoid thermal runaway.
- 11. a) Derive the expression for Stability Factor S of a Fixed Bias Circuit.

b) Derive the expression for Stability Factor S of a Collector to Base Bias Circuit.

[L2][CO3][5M] [L1][CO3][5M] [L2][CO3][5M] [L3][CO3][10M] [L3][CO3][5M] [L3][CO3][5M]

<u>UNIT- IV</u> SMALL SIGNAL LOW FREQUENCY TRANSISTOR AMPLIFIER ANALYSIS

I. Two Mark Questions: 1. What are the salient features of hybrid parameters?	[L1][CO4][2M]
2. Write the hybrid parameters conversion formulae for CC configuration in terms of	
CE configuration. 3 Mention the hybrid parameters conversion formulae for CB configuration in terms of	[L2][CO4][2M]
CE configuration.	
4. Draw the generalized hybrid model for BJT amplifier.	[L2][CO4][2M]
5. Write the expression for current gain A _I for common emitter transistor.	[L2][CO4][2M]
7. For a CE amplifier, if $h_{fe} = 50$, $h_{oe} = 25 \times 10^{-6}$ with load resistance of $R_L = 1k\Omega$,	
Calculate current gain A _I .	[L3][CO4][2M]
8. Draw the approximate CE hybrid model of BJT.	[L2][CO4][2M]
9. Draw the simplified hybrid model for CC amplifier. 10. Draw the circuit diagram for single stage RC coupled amplifier using BJT.	[L2][CO4][2M] [L2][CO4][2M]
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II. Part – B Questions:	
hybrid model for CE transistor and derive the parameters	[L2][CO4][5M]
b) Compare the CE, CB and CC transistor amplifier parameters.	[L2][CO4][5M]
2. Using low frequency h-parameter model, derive the expressions for voltage gain, curre	ent gain,
3 a) With neat diagram derive the CE amplifier parameters using approximate analysis	[L3][CO4][10M] [L2][CO4][5M]
b) Obtain the expressions for current gain, voltage gain, input impedance and output in	npedance of
CB amplifier using simplified hybrid model.	[L2][CO4][5M]
4. a) Determine the parameters A_I , R_i , A_v and R_0 of Emitter Follower using simplified hy analysis	brid model
b) A voltage source of internal resistance $R_s = 900\Omega$ drives a CC amplifier using load r	resistance
R_L =2000 Ω . The CE h parameters are h_{fe} =60, h_{ie} =1200 Ω , h_{oe} = 25 μ A/V and h_{re} = 2	x 10 ⁻⁴ .
Compute A _I , R _i , A _v and R ₀ using approximate analysis. 5 A CE amplifier is driven by a voltage source of internal resistance $R_{i} = 8000$ and the l	[L3][CO4][5M]
impedance of R _L =1000 Ω . The h-parameters are h _{ie} =1k, h _{fe} =50, h _{oe} = 25 μ A/V and h _{re} =	= 2 x 10 ⁻⁴ .
Calculate current gain, voltage gain, input impedance and output impedance using exact	ct
analysis and approximate analysis. 6 For a CB transistor amplifier driven by a voltage source of internal resistance $\mathbf{R} = 120$	[L3][CO4][10M]
Impedance of $R_L = 1000\Omega$. The h parameters are $h_{ib} = 22\Omega$, $h_{rb} = 3 \times 10^{-4}$, $h_{fb} = -0.98$,	$h_{ob} =$
0.5µA/V. Calculate current gain, voltage gain, input impedance and output impedance	using exact
analysis and approximate analysis. 7 Consider a single stage CE amplifier with $\mathbf{P}_{1} = 1k\mathbf{Q}_{1}\mathbf{P}_{2} = 50k\mathbf{Q}_{2}\mathbf{P}_{2} = 2k\mathbf{Q}_{1}\mathbf{P}_{2} = 1k\mathbf{Q}_{2}$	[L3][CO4][10M]
$1.2k\Omega$, $h_{fe}=50$, $h_{ie}=1.1k$, $h_{oe}=25\mu A/V$ and $h_{re}=2.5 \times 10^{-4}$, as shown in Fig. Find A _I , R	$\mathbf{K}_{\mathrm{L}} = \mathbf{K}_{\mathrm{i}}, \mathbf{A}_{\mathrm{v}}, \mathbf{A}_{\mathrm{vs}}, \mathbf{K}_{\mathrm{vs}}, \mathbf{K}_{\mathrm{vs}}$
A_{IS} and R_0 .	[L3][CO4][10M]
e+V _{cc}	



8. a) Obtain the expression for current gain, voltage gain, input impedance and output impedance For Common Emitter Amplifier with Emitter Resistor. [L2][CO4][5M] b) A CE amplifier is driven by a voltage source of internal resistance $R_s = 1000\Omega$ and the load impedance of R_C=2k Ω . The h-parameters are h_{ie}=1.3k, h_{fe}=55, h_{oe} = 22 μ A/V and $h_{re} = 2 \times 10^{-4}$. Neglecting biasing resistors, compute current gain, voltage gain, input impedance, output impedance for the value of Emitter Resistor $R_E = 200\Omega$ inserted in the emitter circuit. [L3][CO4][5M] 9. a) Draw the circuit diagram of a single stage RC coupled Amplifier and discuss the steps used for designing it. [L2][CO4][5M] b) Determine Voltage Gain, Current Gain, Input resistance and Output resistance for a CE amplifier using NPN transistor with $h_{ie} = 1200\Omega$, $h_{re} = 0$, $h_{fe} = 36$ and $h_{oe} = 2 \times 10^{-6}$ mhos, $R_L = 2.5 k\Omega$ and $R_{\rm S} = 500\Omega$ (neglect the effect of biasing circuit). [L3][CO4][5M] 10. Design a single stage RC coupled BJT amplifier for the following values. Assume that for Silicon transistor, $V_{cc} = 10V$, $I_c = 4mA$, $h_{fe} = 100$, $h_{ie} = 1k\Omega$, $R_{L} = 100k\Omega$ and $f_L = 100Hz$. [L3][CO4][10M]

<u>UNIT- V</u> FIELD EFFECT TRANSISTOR

I. Two Mark Questions:

1. Why a Field Effect Transistor is called so? [L1][CO5][2M] 2. Mention the advantages of FET? [L2][CO5][2M] 3. Define Pinch off Voltage. [L1][CO5][2M] 4. Define drain resistance of JFET. [L1][CO5][2M] 5. What is transconductance of JFET. [L1][CO5][2M] [L1][CO5][2M] 6. What is MOSFET? Classify the types of MOSFET. 7. Draw the symbol for depletion and enhancement n channel MOSFET. [L2][CO5][2M] 8. Draw the drain characteristics of n-channel enhancement MOSFET. [L2][CO5][2M] 9. What is the need for oxidation process in IC fabrication. [L2][CO5][2M] 10. What do you mean by photolithography in IC fabrication process? [L1][CO5][2M] **II.** Part – B Questions: 1. a) Describe the construction and working principle of N-channel JFET. [L2][CO5][8M] b) Mention the applications of JFET. [L1][CO5][2M] 2. a) Define the JFET Volt-Ampere Characteristics and determine FET parameters. [L1][CO5][5M] b) Compare the performance of BJT with FET. [L3][CO5][5M] 3. a) With the help of neat diagram, explain the operation and characteristics of n-channel enhancement type MOSFET. [L2][CO5][8M] b) Mention the differences between depletion and enhancement MOSFET. [L3][CO5][2M] 4. Discuss the operation and characteristics of n-channel depletion type MOSFET with diagram. [L2][CO5][10M] 5. a) Draw and explain the small signal model of FET at low frequency. [L1][CO5][4M] b) For the circuit shown in Fig. determine input impedance, output impedance and voltage gain. [L4][CO5][6M] g_m = 2 mS



6. Derive input impedance, output impedance and voltage gain of JFET Common Drain amplifier with neat diagram.

[L2][CO5][10M]

- 7. a) Discuss JFET Fixed Bias with neat diagram and derive the expression for Input impedance, Output impedance and Voltage gain. [L3][CO5][8M] [L3][CO5][2M]
 - b) Compare n channel JFET with p channel JFET.
- 8. a) Draw the circuit diagram of JFET Common Source amplifier with voltage divider bias for bypassed Rs and determine the expression for input impedance, output impedance and voltage gain. [L2][CO5][5M]
 - b) For Common Drain Amplifier as shown in the Figure, $g_m = 2.5 \text{mS}$, $r_d = 25 \text{K}\Omega$. Calculate Input impedance, Output impedance and Voltage gain. [L4][CO5][5M]



9. List and explain the steps involved in the manufacturing process of monolithic ICs. 10. Discuss CMOS fabrication process with neat diagram.

[L2][CO5][10M] [L1][CO5][10M]

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QUESTION BANK (OBJECTIVE)

Subject with Code : Electronic Devices (18EC04	401) Course & Branch: B.Tech	h - ECE	š
Year & Sem: II-B.Tech & I-Sem	Regulation: R18		
	<u>UNIT –I</u>		
<u>PN JUN</u>	CTION DIODE	F	-
1. The static resistance of a diode is		L	J
A) its opposition to the DC current flow	B) its opposition to the AC current flow		
C) resistance of diode when forward biased	D) none of the above	_	_
2. When the reverse bias is applied to a junction d	iode, it [GATE 2015]]
A) lowers the potential barrier	B) raises the potential barrier		
C) greatly decreases the minority carrier current	t D) greatly increases the minority carrier cur	rent	_
3. Doping of semiconductor is		[]
A) the process of purifying semiconductor mate	erials		
B) the process of adding certain impurities to th	e semiconductor material in controlled amoun	ts	
C) the process of converting semiconductor mat	terial into some form of active device such as	FET	
D) one of the steps used in the fabrication of IC	S		
4. Referring to the energy level diagram of semico	onductor materials, the width of forbidden ener	rgy	
gap is about [GATE 2003]		[]
A) 10eV B) 100eV C) 1e	eV D) 0.1eV		
5. A PN junction diode [IES 2014]		[]
A) has high resistance in both forward and rever	rse directions		
B) has low resistance in the forward direction			
C) has high resistance in the forward direction			
D) has low resistance in the reverse direction			
6. If a PN junction is not biased, the junction curre	ent at equilibrium is	[]
A) zero as no charges cross the junction			
B) zero as equal number of carriers cross the ba	rrier		
C) mainly due to diffusion of majority charge ca	arriers		
D) mainly due to top diffusion of majority charge	ge carriers		
7. In a PN junction, the potential barrier is due to t	the charges on either side of the junction,		
which consists of		[]
A) fixed donor and acceptor ions B) m	ajority carriers only	-	_
C) minority carriers only D) be	oth majority and minority carriers		
8. In a PN junction, the region containing the unco	ompressed acceptor and donor ions		
is called [GATE 2007]	1 1	Γ	1
A) transition zone B) depletion region C) ne	eutral region D) active region	-	_
9. In a forward biased PN junction diode, the		Γ	1
A) positive terminal of the battery is connected	to the P side and the negative to the N side	-	-
B) positive terminal of the battery is connected	to the N side and the negative to the P side		
C) junction is earthed	C		
D) none of the above			
10. When PN junction is forward biased		ſ	1
A) electrons in the N region are injected into the	e P region	L	-
B) holes in the P region are injected into the N I	region		
C) both (a) and (b)	C		
D) None of the above			
11. When we apply reverse bias to a junction diod	e. it	Γ	1
A) lowers the potential barrier	B) raises the potential barrier	L	L
C) greatly decreases the minority carrier current	nt D) greatly increases the majority carrier of	irrent	
12. Under normal operating voltage, the reverse cu	urrent in a silicon diode is about	[1

	A) 10mA B) $1\mu\text{A}$ C) $1000\mu\text{A}$ D) None of the above		_
13.	. The increased depletion region in a PN diode is due to [GATE 2015]	[]
	A) reverse biasing B) forward biasing		
	C) an area created by crystal doping D) an area void of current carriers		
14.	. When a diode is forward biased,	[]
	A) barrier potential increases B) barrier potential decreases		
	C) majority current decreases D) minority current decreases		
15	For a Germanium PN junction, the maximum value of barrier potential is [IES 2009]	ſ	1
10.	A) $0.3V = B$) $0.7V = C$) $1.3V = D$) $1.7V$	L	Т
16	For a Silicon PN junction, the maximum value of harrier potential is [CATE 2015]	r	1
10.	A = A = A = A = A = A = A = A = A = A =	L	1
17	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	г	1
17.	. when noise leave the p material to fill electrons in the n material, the process is called	L]
10	A) mixing B) depletion C) diffusion D) none of the above	F	-
18.	. The decreased depletion region in a PN junction is due to	L]
	A) reverse biasing B) forward biasing		
	C) diffusion D) none of the above		
19.	. Current flow in a semiconductor depends on the phenomenon	[]
	A) drift B) diffusion C) recombination D) All of the above		
20.	. In a semiconductor diode, $V - I$ relationship is such that	[1
	A) current varies linearly with voltage B) current increases exponentially with volt	age	1
	C) current varies inversely with voltage D) none of these	0	
21	The canacitance appearing across a reverse biased semiconductor junction [GATE 2001]	ſ	1
21.	A) increases with increase in bias voltage B) decreases with increase in bias v	l Itage	1
	C) is independent of bias voltage D) none of these	mage	
22	C) is independent of bias voltage D) none of these	г	ı
22.	A) measing device D) are some taken C) and it taken D) hild and d	L.]
22	A) passive device B) vacuum tube C) unnateral device D) bilateral de	evice	
23.	A certain amount of diode current still flows when diode is under reverse bias condition.	r	-
	What is this current called?	L	l
	A) Reverse bias current B) Reverse saturation current		
	C) Reverse diode Current D) Diode off current		
24.	. The number of minority carriers crossing the junction of a PN junction diode depends		
	Primarily on [GATE 2013]	[]
	A) concentration of doping impurities B) magnitude of potential barrier		
	C) magnitude of forward bias voltage D) rate of thermal generation of electron ho	le pairs	
25.	. Reverse saturation current in a germanium diode is of the order of	[]
	A) 1nA B) 1µA C) 1mA D) 10mA		
26.	. The diffusion capacitance of a forward biased PN junction diode with a steady current I		
	demende en (CATE 1997)		
	depends on (GATE 1987)	[]
	A) width of the depletion region B) mean lifetime of holes	[]
	depends on (GATE 1987)A) width of the depletion regionB) mean lifetime of holesC) mean lifetime of electronsD) junction area	[]
27.	depends on (GATE 1987)A) width of the depletion regionB) mean lifetime of holesC) mean lifetime of electronsD) junction area	[]
27.	depends on (GATE 1987)A) width of the depletion regionB) mean lifetime of holesC) mean lifetime of electronsD) junction area. Zener breakdown occursA) due to normally generated carriersB) in lightly doped junctions	[]
27.	depends on (GATE 1987)A) width of the depletion regionC) mean lifetime of electronsD) junction areaZener breakdown occursA) due to normally generated carriersC) due to rupture of covalent bondsD) mostly in germanium junctions	[]
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27.28.29.30.31.	depends on (GATE 1987)A) width of the depletion regionB) mean lifetime of holesC) mean lifetime of electronsD) junction areaZener breakdown occursB) in lightly doped junctionsA) due to normally generated carriersB) in lightly doped junctionsC) due to rupture of covalent bondsD) mostly in germanium junctionsA breakdown which is caused by cumulative multiplication of carriers through field inducedImpact ionization occurs in (GATE 2015)A) Zener diodeB) Tunnel DiodeC) Varactor DiodeD) Avalanche DiodeFor a highly doped diode (GATE 1989)A) Zener breakdown is like to take placeB) Avalanche breakdown is like to take placeC) either (a) or (b) will take placeD) neither (a) or (b) will take placeThe breakdown that occurs in the reverse biased condition in a narrow junction diode isA) Zener BreakdownB) Avalanche BreakdownC) both (a) and (b)D) No	[[[ce [ne []]]]]
 27. 28. 29. 30. 31. 	depends on (GATE 1987)A) width of the depletion regionB) mean lifetime of holesC) mean lifetime of electronsD) junction area. Zener breakdown occursB) in lightly doped junctionsA) due to normally generated carriersB) in lightly doped junctionsC) due to rupture of covalent bondsD) mostly in germanium junctions. A breakdown which is caused by cumulative multiplication of carriers through field inducedImpact ionization occurs in (GATE 2015)A) Zener diodeB) Tunnel DiodeC) Varactor DiodeD) Avalanche Diode. For a highly doped diode (GATE 1989)A) Zener breakdown is like to take placeB) Avalanche breakdown is like to take placeC) either (a) or (b) will take placeD) neither (a) or (b) will take place. The breakdown that occurs in the reverse biased condition in a narrow junction diode isA) Zener BreakdownB) Avalanche BreakdownC) both (a) and (b)D) No. The breakdown that occurs in the reverse biased condition in a wider junction diode isA) Zener BreakdownB) Avalanche BreakdownC) both (a) and (b)D) No	[[[ce [ne [ne] ne]]]]
 27. 28. 29. 30. 31. 32. 	depends on (GATE 1987)A) width of the depletion regionB) mean lifetime of holesC) mean lifetime of electronsD) junction area. Zener breakdown occursB) in lightly doped junctionsA) due to normally generated carriersB) in lightly doped junctionsC) due to rupture of covalent bondsD) mostly in germanium junctions. A breakdown which is caused by cumulative multiplication of carriers through field inducedImpact ionization occurs in (GATE 2015)A) Zener diodeB) Tunnel DiodeC) Varactor DiodeD) Avalanche Diode. For a highly doped diode (GATE 1989)A) Zener breakdown is like to take placeB) Avalanche breakdown is like to take placeC) either (a) or (b) will take placeD) neither (a) or (b) will take place. The breakdown that occurs in the reverse biased condition in a narrow junction diode isA) Zener BreakdownB) Avalanche BreakdownC) both (a) and (b)D) No. The breakdown that occurs in the reverse biased condition in a wider junction diode isA) Zener BreakdownB) Avalanche BreakdownC) both (a) and (b)D) No. The Volt Equivalent Temperature V _T for a room temperature is [GATE 2010]	[[[ce [ne [ne [ne [ne]]]]]

33. Practically, the value of dV/dT is assumed to be for either Ge or Si at room	
Temperature.	[]
A) $-2.5 \text{mV/}^{0}\text{C}$ B) $-4.7 \text{mV/}^{0}\text{C}$ C) $-26 \text{mV/}^{0}\text{C}$ D) none of the above	
34. The reverse saturation current I_0 increases by change in temperature for both Si and	Ge
Diodes.	[]
A) 10% per ${}^{0}C$ B) 7% per ${}^{0}C$ C) 2.3% per ${}^{0}C$ D) 20% per ${}^{0}C$	
35. The reverse saturation current approximately doubles for every rise in temperature.	[]
A) 30° C B) 20° C C) 10° C D) none of the above	
36. The circuit with which the waveform is shaped by removing a portion of the input signal	
Without distorting the remaining part of AC signal is called	[]
A) Clamper B) Multivibrator C) Clipper D) None of the above	
37. Clipping circuits are also called as	[]
A) Voltage or Current limiter B) Amplitude Selector C) Slicers D) All of the above	
38. If a small portion of positive or negative half cycle of the signal voltage is to be removed, the	n
the type of clipper used is	[]
A) Biased Clipper B) Positive Clipper C) Negative Clipper D) none of the above	г - 1
39. A circuit which introduces a DC level to an AC signal is called	[]
A) Clipper B) Clamper C) Tuned Amplifier D) Blocking Oscillator	г 1
40. A dc restorer is a	I]
A) Chipper B) Tuned Amplifier C) Clamper D) Blocking Oscillator	
LINIT II	
<u>UNII -11</u> Dectifieds fil teds & sdecial duddase devices	
1 A rectifier is used to	۲ I
A) convert AC voltage to DC Voltage (B) convert DC voltage to AC Voltage	L]
C) both (a) and (b) D) convert voltage to rice voltage	
2. The ripple factor of a Half Wave Rectifier is	۲ I
A) 1.21 B) 0.482 C) 0.406 D) 0.121	LJ
3. The peak inverse voltage of a Half Wave Rectifier is	[]
A) V_m B) 2 V_m C) $V_m/2$ D) $3V_m$	
4. The efficiency of a Half Wave Rectifier is	[]
A) 40.6% B) 81.2% C) 1.12% D) 48.2%	
5. The ripple factor of Full wave rectifier is [IES 2012]	[]
A) 1.21 B) 0.482 C) 0.406 D) 0.121	
6. The peak inverse voltage of a full Wave Rectifier is [GATE 2004]	[]
A) V_m B) 2 V_m C) $V_m/2$ D) $3V_m$	
7. The efficiency of a full Wave Rectifier is	[]
A) 40.6% B) 81.2% C) 1.12% D) 48.2%	
8. The peak inverse voltage of a Bridge Rectifier is	[]
A) V_m B) 2 V_m C) $V_m/2$ D) $3V_m$	
9. The bridge rectifier requires [GATE 2001]	
A) 2 diodes B) 3 diodes C) 4 diodes D) 8 diodes	г - 1
10. The primary function of a rectifier filter is to	[]
A) suppress old narmonics B) remove ripples	
(1) Stabilize the output de level (D) minimize the input ac variations	г л
A) the same as that as Helf wave circuit B) Double as that of a helf wave	L J
(C) definitely more but less than double that of a half wave circuit (C) pone of these	
12 In a full wave rectifier circuit, the peak inverse voltage per diode is	۲ I
A) the same as that is a half wave rectifier circuit B) half the value in half wave rectifier	er circuit
C) double the value in half wave rectifier circuit D) none of these	encon
13. In a half wave rectifier circuit, the load current flows [GATE 1997]	[]
A) only for the positive half cycle of the input signal	- 1
B) for less than half cycle of the input signal	
C) for more than half cycle of the input signal	
D) for whole cycle of the input signal	
· · · ·	

14.	In a full wave bridge rectifier, if V_m is the PIV across the secondary of the transformer, the		
	maximum voltage coming across each reverse biased diode is	[]
	A) V_m B) 2 V_m C) $V_m/2$ D) None of these		
15.	In capacitor filter, the ripple factor decreases with [GATE 2011]	[]
	A) decrease in C B) increase in C		
	C) increase in frequency D) decrease in frequency		
16.	The diode used in voltage regulator is	[]
	A) PN junction diode B) Varactor Diode C) Zener Diode D) GUNN dio	de	
17.	The ripple factor of a inductor filter is	[]
	A) $R_L w/(\sqrt{2}\sqrt{3}L)$ B) $R_L/(\sqrt{2}\sqrt{3}L)$ C) $R_L/(3\sqrt{2}wL)$ D) $R_L/(2\sqrt{3}wL)$		
18.	A half wave rectifier is equivalent to [GATE 2006]	[]
	A) a clamper circuit B) a clipper circuit		
	C) a clamper circuit with negative bias D) a clamper circuit with positive bias		
19.	The basic reason why a full wave rectifier has a twice the efficiency of a half wave rectifier		
	is that :[GATE 1997]	[]
	A) it makes use of transformer B) its ripple factor is much less		
• •	C) it utilizes both half cycle of the input D) its output frequency is double the line fre	quency	r _
20.	The DC power output for HWR is	[]
	A) $(I_m^2/\pi^2)R_L$ B) $I_m/2$ C) $(I_m/2) R_L$ D) $I_m.R_L$	_	_
21.	The TUF for Bridge Rectifier is	[]
	A) 0.287 B) 0.693 C) 0.812 D) 0.963		
22.	The amount of ac content in the output can be mathematically expressed by a factor called	[]
	A) TUF B) Ripple factor C) PIV D) PRV	_	_
23.	The TUF for HWR is [BSNL(TTA) 2015]]
	A) 1.211 B) 0.86 C) 0.287 D) 0.911	_	_
24.	Zener diode is usually operated [GATE 1989]	[]
	A) in forward bias mode B) in reverse bias mode		
	C) near cut in voltage D) in forward linear region	_	_
25.	Which one of the following diode is used for voltage stabilization? [GATE 2011]]
	A) PN Junction B) Tunnel C) Varactor D) Zener	_	_
26.	Which of the following statement is best suited for a Zener diode?]
	A) It is rectifier diode B) It works in the forward biased region		
~=	C) It is a constant voltage device D) It is mostly used in clipping circuit	r	-
27.	A tunnel diode	L]
	A) is a reverse recovery diode B) has heavy doping		
20	C) is a power diode D) has light doping	r	ч
28.	Which one of the following diodes shows the negative resistance region? [GATE 2002]	L]
20	A) PN Junction B) Tunnel C) Zener D) Varactor	г	ч
29.	I he most important application of a Tunnel diode is	L]
20	A) rectifier B) switching device C) voltage controlled device D) none of the	r se	1
30.	A) multivulued function of voltage	L]
	A) multivalued function of voltage B) multivalued function of current D) none of these		
21	() single value function of current (D) none of these	г	1
51.	A) they have high operations can tunner through a PN junction is that [GATE 2009]	L]
	A) they have high energy B) darner potential is very low		
22	The L / L ratio of typeal diada is of primary importance in	г	1
32.	The I_p / I_v ratio of tunnel diode is of primary importance in A) determining tunneling speed of electrons B) the design of an oscillator	L	1
	C) amplifier designing		
33	Silicon is preferred for manufacturing Zener diodes because	г	1
55.	A) is relatively cheap B) needs lower doping level	L	1
	C) has high temperature and current capacity D) has lower breakdown voltage		
3/1	I FDs are fabricated from	ſ	1
54.	A) silicon B) germanium C) Si or Ge D) gallium arcenide	L	1
35	A photodiode is used in reverse bias because	ſ	1
55.	A) majority swept are reverse across the junction	L	T

B) only one side is illuminated	
C) reverse current is small when compared to pho	tocurrent
D) reverse current is large when compared to pho	tocurrent
36. Which one of the following statement is correct?	A photo diode works on the
principle of [GATE 1990]	[]
A) photovoltaic effect B) photoconductiv	e effect
C) photoelectric effect D) photothermal effect	fect
37. A LED is basically which one of the following b	iased PN Junction? []
A) forward biased B) reverse biased C) light	ly doped D) heavily doped
38. GaAs LEDs emit radiation in the [GATE 1992]	[]
A) ultraviolet region B) violet blue gree	n range of the visible region
C) visible region D) infra red region	
39. A Varactor diode is also called as	[]
A) Voltage variable capacitor B) TRIAC C) DIAC D) none of the above
40. Solar cell works under the principle of	[]
A) Hall Effect B) piezo electric effect C)	Photovoltaic Effect D) none of the above
<u>UN</u>	NIT III
BIPOLAR JUNC	<u>FION TRANSISTOR</u>
1. A collector collects	[]
A) electrons from the base in case of PNP transiste	ors
B) electrons from the emitter in case of PNP trans	istors
C) holes from the base in case of NPN transistors	
D) holes from the base in case of PNP transistors	
2. In a PNP transistor with normal bias, [GATE 201	5] []
A) the collector junction has negligible resistance	
B) only holes cross the collector junction	
C) the CB junction is reverse biased and the EB ju	nction is forward biased
D) only majority carriers cross the collector juncti	on
3. A PNP transistor is made of [GATE 2004]	[]
A) Silicon B) Germanium C) eithe	er silicon or Germanium D) none of the above
4. In most transistors, the collector region is made pl	hysically larger than the emitter
Region	
A) for dissipating heat	
B) to distinguish it from others	
C) as it is sensitive to ultraviolet rays	
D) to reduce resistance in the path of flow of elect	rons
5. The three terminals of a BJT are called	[]
A) PNP B) NPN C) anode, cathode and	gate D) emitter, base and collector
6. For a NPN transistor, the N regions are	
A) emitter and base B) base and collector	C) emitter and collector D) None
7. For operation of PNP amplifier, the base of the an	plifier must be []
A) 0 V	B) positive with respect to collector
C) negative with respect to collector	D) greater than the collector current
8. In a transistor, the region that is very lightly doped	and very thin is the []
A) emitter B) base C) collector	D) None of the above
9. In a NPN transistor, the emitter	,
A) emits or injects holes into the collector	B) emits or injects electrons into the collector
C) emits or injects holes into the base	D) emits or injects holes into the base
10. In a PNP transistor with normal bias, the emitter	iunction
A) is always reverse biased	B) offers very high resistance
C) offers a low resistance	D) remains open
11. In a NPN transistor, when the emitter junction is	forward biased and the collector junction
Is reverse biased, the transistor will operate in the	e [GATE 1995] []
A) active region B) saturation region	C) cutoff region D) None of the above
12. In a PNP transistor, electrons flow	

A) into the transistor at the collector only	
B) into the transistor at the base and the collector leads	5
C) out of the transistor at the base and the collector lea	ds
D) out of the transistor at the base collector as well as	emitter leads
13. The arrow head on a transistor symbol indicates	[]
A) direction of electron current in the emitter	B) direction of hole current in the emitter
C) diffusion current in the emitter	D) drift current in the emitter
14. Power transistors are invariably provided with	
A) soldered connections B) Heat Sink	C) metallic casting D) None
15. The largest current flow of a bipolar transistor occurs	,
A) in emitter B) in base C) in collector	D) through emitter-collector
16. Conventional biasing of a bipolar transistor has [GAT	E 20071 []
A) EB forward biased and CB forward biased B) EI	B reverse biased and CB forward biased
C) EB forward biased and CB reverse biased D) El	B reverse biased and CB reverse biased
17. The common emitter transistor circuit has]
A) high gain B) low gain C) negli	gible gain D) zero gain
18 In an NPN transistor if both the emitter junction and o	collector junction are reverse biased
then the transistor will operate in	
A) active region B saturation region C cutof	f region D) none of the above
19 In a normally biased NPN transistor, the main current	crossing the collector
iunction is	
(A) a drift current (B) a hole current (C) a diffu	sion current D) same as base current
20 In a PNP transistor, the electrons flow into the transist	or at the
(A) collector only (B) emitter only (C) emitter	r and base D) collector and base
21 The forward current gain he is defined as	r and base D) concetor and base
21. The following current gain, Π_{fe} , is defined as A) V_{ee} / I_e , V_{ee} constant B) I_e / I_e	V == constant
A) v_{BE} / I_B , v_{CE} constant D) I_B / I_C , C) I_a / I_a V = constant D) I_b / I_c	V _{CE} constant
C) I_C / I_B , V_{CE} constant D) I_C / I_B , 22 The g and B of a transistor are related to each other as	
22. The α and β of a transistor are related to each other as $A) \alpha = \beta / (1 + \beta) \qquad D) \beta = \alpha / (1 + \alpha) \qquad C) \beta = (1 + \alpha)$	$(1 + \beta) / \beta$
A) $\alpha = p/(1+p)$ B) $p = \alpha/(1+\alpha)$ C) $p = (1+\alpha)$ 22 The transistor configuration which provides highest of	$(\alpha - \alpha)/\alpha = D/\alpha - (1+p)/p$
25. The transistor configuration which provides highest of	an Collector D) None of the above
A) Common base b) Common Emitter C) Common 24 For $\alpha = 0.00$ the value of β is [C ATE 2007]	JI Conector D) None of the above
24. For $\alpha = 0.99$, the value of p is [GATE 2007]	D) 100
A) 9.9 B) 49 C) 99	D) 100
25. The operating point variation is due to $(A = A)$ $(A = B)$ All the sh	
A) I_{co} B) V_{BE} C) p D) All the do	ove
26. Which of the following conditions ensures that the tra	isistor does not undergo thermal
$\frac{1}{2}$	
A) $V_{CE} = V_{CC} / 2$ B) $V_{CE} < V_{CC} / 2$ C) $V_{CC} = V_{CC} / 2$	$c_{\rm E} < v_{\rm CC}$ D) $v_{\rm CE} > v_{\rm CC} / 2$
27. The stability factor of a fixed bias is (2)	
A) $1 + \beta$ B) $1 - \beta$ C) β	$1 - \beta$ D) $1 / 1 - \beta$
28. The leakage current in CE configuration may be arour	
A) rew nanoamperes B) rev	w microamperes
C) few hundred microamperes D) fe	w milliamperes
29. The quiescent point of a transistor biasing circuit impl	
A) zero bias B) no output C) no distort	on D) no input signal
30. For normal amplification, the Q-point should be established	ished in the []
A) active region B) saturation region C) cutoff reg	ion D) none of the above
31. The biasing technique which gives good stability is [G	ATE 2015]
A) Collector to base bias B) Fixed Bias C) Se	If Bias D) none of the above
32. Stability factor S is approximately unity for	
A) Collector to base bias B) Fixed Bias C) Se	If Bias D) none of the above
33. Which of the following transistor parameters are funct	ions of temperature: []
A) β alone B) I _{CO} alone C) V _{BE} alone	D) all of the above
34. The self bias arrangement gives an improved Q-point	stability when []
A) R_E is low B) β is small, but R_E is large	C) both β and R _E are large D) none
35. The biasing method which is considered independent of	of transistor β is [GATE 1990] []

A) fixed bias B) collector feedback l 36. The biasing configuration that offers least	oias t stability is	C) voltage divid	er bias	D) none	1
A) fixed bias B) collector feedback l	pias	C) voltage divid	er bias	D) none	
37. Which one of the following statements is	correct? [GA]	FE 2011]		[]
A) Both I_{CO} and V_{BE} increase with temperature A	erature				
B) Both I_{CO} and V_{BE} decrease with temperature of V_{BE}	erature				
C) I_{CO} increases with temperature and V_1	BE decreases w	ith temperature			
38 The collector current for the CE circuit is	BE increases w given $L = \beta I_p$	$+(1+\beta)$ L _{co} Th	e three variab	hles	
B. In and L_{∞} [GATE 2013]	given ic biB	· (1 · p) 100. 11		лез Г	1
A) increase with rise in temperature	B) incr	ease with fall in	temperature	L	1
C) decrease with rise in temperature	D)decr	ease with fall in	temperature		
39. The resistance of thermistor decreases exp	ponentially wit	h	1	[1
A) increase of temperature B) decrease	of temperature	e C) con	istant tempera	ature D) no	one
40. The stability factor S is				[]
A) dI_c / dI_{c0} B) dI_c / dV_{BE}	C) $dI_c / d\beta$	D) none	of the above		
SMALL SIGNAL LOW EDEOL	UNIT IV	ISISTOD AMD	I IFIFD ANA	I VCIC.	
1 h parameters are also called as	ENCI IKAP	51510K AMP.	LIFICK ANA	<u>11 1 515:</u> [1
A) admittance parameters		B) hybrid param	neters	L	1
C) impedance parameters		D) reluctance participation	rameters		
2. The parameter h_{11} has the dimension of		_)		ſ	1
A) $\hat{\Omega}$ B) \mho C) V	D) dimensionle	ess		L	-
3. The parameter h_{12} has the dimension of				[]
A) Ω B) \mho C) V	D) dimensionle	ess			
4. The parameter h_{21} has the dimension of				[]
A) Ω B) \mho C) V	D) dimensionle	ess			
5. The parameter h_{22} has the dimension of				[]
	D) dimensionle	ess		г	1
b. The parameter h_i is called as		na valtaga gain	D) formula	L Surrant gain]
7 The parameter h is called as [CATE 1005]	lice C) level	se voltage gam	D) for ward C		1
A) input impedance B output admitta	ı nce C) rever	se voltage gain	D) forward (L Surrent gain	1
8. The parameter h_f is called as		se voltage gam	<i>D</i>) for ward C	/urrent guin [1
A) input impedance B) output admitta	nce C) rever	se voltage gain	D) forward c	current gain	1
9. The parameter h_0 is called as	,	00	,	[]
A) input impedance B) output admitta	nce C) rever	se voltage gain	D) forward c	current gain	
10. The amplifier that gives unity voltage gai	n is [GATE 2 0)17]		[]
A) common emitter B) common colle	ctor C) comm	non base D) o	common gate		
11. The amplifier that gives maximum power	gain is [IES 2	014]		[]
A) common emitter B) common colle	ctor C) comm	non base D) o	common gate	г	-
12. The amplifier that gives 180° phase shift	is [IES 2011]	non haan D)		l]
A) common collector amplifier is also a	C(OT C) COMM	$\frac{100}{100}$	common gate	г	1
A) collector follower B) base Follower	C emitter f	C 1994j Follower D) n	one of the abo]
14 The h parameters approach gives correct	results for			Γ	1
A) Large Signals only B) Small Signal	ls only C) Be	oth large and sm	all signals – Г)) none	1
15. An emitter follower is used as]	1
A) a power amplifier	B) an impedan	ce matching dev	ice	L	-
C) a low input impedance circuit) a follower of	f base signal			
16. The expression for current gain A_I for CE	amplifier is	-		[]
$A) - h_{fe} / (1 + h_{oe}R_L) \qquad B) A_iR_L / Z_i$	C) $h_{ic} + h_{rc}$	$A_i R_L$ D) h_{oe} -	$- [(h_{fe}h_{re}) / (h_{ie})]$	$(e + R_s)$]	
17. The expression for voltage gain A_V for C	B amplifier is		- / - - - - -]]
A) $-h_{fe} / (1 + h_{oe}R_L)$ B) A_iR_L / Z_i	C) $h_{ic} + h_{rc}$	$A_i R_L D) h_{oe} - $	$- \lfloor (h_{fe}h_{re}) / (h_{ie}) \rfloor$	$(e + K_s)$	7
18. The expression for input impedance Z_I fo	r CC amplifier	18		l]

$ A) - h_{fe} / (1 + h_{oe}R_L) $ $ B) A_iR_L / Z_i $ $ C) h_{ic} + h_{rc} A_i R_L $ $ D) h_{oe} - [(h_{fe}h_{re}) / (h_{ie} + R_i) A_i R_L $,)]	
19. The expression for output admittance Y_o for CE amplifier is	[]
$ A) - h_{fe} / (1 + h_{oe}R_L) $ $ B) A_iR_L / Z_i $ $ C) h_{ic} + h_{rc} A_i R_L $ $ D) h_{oe} - [(h_{fe}h_{re}) / (h_{ie} + R_i) + R_i R_L $.)]	
20. The relation between A_{vs} and A_{is} is	[]
A) $A_{vs} = A_{is} R_L / R_s$ B) $A_{vs} = A_{is}$ C) $A_{vs} = R_L / R_s A_{is}$ D) $A_{vs} = h_i h_o / A_{is}$		
21. In simplified hybrid model of CE, the current gain is	[]
A) $-h_{fe}$ B) $A_i R_L / h_{ie}$ C) h_{ie} D) infinity		
22. In simplified hybrid model of CE, the voltage gain is	[]
A) $-h_{fe}$ B) $A_i R_L / h_{ie}$ C) h_{ie} D) infinity		
23. In simplified hybrid model of CE, the input impedance is	[]
A) $-h_{fe}$ B) $A_i R_L / h_{ie}$ C) h_{ie} D) infinity	_	_
24. In simplified hybrid model of CE, the output impedance is		
A) $-h_{fe}$ B) $A_i R_L / h_{ie}$ C) h_{ie} D) infinity	r	
25. In simplified hybrid model of CB, the current gain is	L]
A) $h_{fe} / (1 + h_{fe})$ B) $h_{fe} R_L / h_{ie}$ C) $h_{ie} / (1 + h_{fe})$ D) infinity		-
26. In simplified hybrid model of CB, the voltage gain is	L	J
A) $h_{fe} / (1 + h_{fe})$ B) $h_{fe} R_L / h_{ie}$ C) $h_{ie} / (1 + h_{fe})$ D) infinity	г	Ъ
27. In simplified hybrid model of CB, the input impedance is $(1 + 1)$ $(1 + 1)$ $(1 + 1)$ $(1 + 1)$	L]
A) $n_{fe} / (1 + n_{fe})$ B) $n_{fe} R_L / n_{ie}$ C) $n_{ie} / (1 + n_{fe})$ D) infinity	г	г
28. In simplified hybrid model of CB, the output impedance is $A = \frac{1}{2} \frac$	L	J
A) $n_{fe} / (1 + n_{fe})$ B) $n_{fe} R_L / n_{ie}$ C) $n_{ie} / (1 + n_{fe})$ D) infinity 20. In simplified herbrid model of CC, the summent asia is	г	1
29. In simplified hybrid model of CC, the current gain is (A) $1 + b_2$ (B) $1 = C$ (b) $+ [(1 + b_2) P_2] = D$ (P + b) $/(1 + b_2)$	L]
A) $I + II_{fe}$ D) I C) $II_{ie} + [(I + II_{fe}) KL]$ D) $(K_s + II_{ie}) / (I + II_{fe})$ 20 In simplified hybrid model of CC, the voltage gain is	г	1
So, in simplified model of CC, the voltage gain is $A = A + b_{1} + b_{2}$ B = $A = A + b_{1} + b_{2}$ (1 + b ₂)	L	Ţ
A) $I + II_{fe}$ D) I C) $II_{fe} + [(I + II_{fe}) K_L]$ D) $(K_s + II_{fe}) / (I + II_{fe})$ 31 In simplified hybrid model of CC, the input impedance is	г	1
Δ) 1 + h _c B) 1 C) h _c + [(1 + h _c) R _z] D) (R + h _c) / (1 + h _c)	L	1
$A = H_{Ie} + D = C + H_{Ie} + (I + H_{Ie}) + (I + H_{Ie})$ 32 In simplified hybrid model of CC the output impedance is	Г	1
A) $1 + hc_1$ B) $1 - C$ $hc_2 + f(1 + hc_2) R_1 = D$ $(R_2 + hc_2) / (1 + hc_2)$	L	1
33 The condition for approximate analysis is	ſ	1
A) $R_{I} = R_{S}$ B) $h_{0.8}R_{I} < 0.1$ C) $h_{i.8} < 0.01$ D) $h_{f.8} = 0$	L	1
34. If the emitter resistance in a common emitter voltage amplifier is not bypassed.		
it will [GATE 2014]	ſ	1
A) reduce both the voltage gain and the input impedance	L	
B) reduce the voltage gain and increase the input impedance		
C) increase the voltage gain and reduce the input impedance		
D) increase both the voltage gain and the input impedance		
35. For simplified CE hybrid model, if $h_{fe} = 60$, $h_{ie} = 500\Omega$ at $I_c = 3$ mA, the input impedance is	[]
A) 300Ω B) $5.1k\Omega$ C) 60Ω D) 500Ω		
36. For simplified CE hybrid model, if $h_{fe} = 60$, $h_{ie} = 500\Omega$ at $I_c = 3mA$, the output impedance is	s []
A) 660Ω B) 45Ω C) $5.1k\Omega$ D) $6.2M\Omega$		
37. For simplified CE hybrid model, if $h_{fe} = 60$, $h_{ie} = 500\Omega$ at $I_c = 3$ mA, the voltage gain is	[]
A) -544 B) -612 C) 455 D) 750		
38. For simplified CE hybrid model, if $h_{fe} = 60$, $h_{ie} = 500\Omega$ at $I_c = 3$ mA, the current gain is	[]
A) -60 B) 88 C) -100 D) 1		
39. In the h parameter model the input and output sections are modeled as [GATE 2000]	[]
A) voltage sources B) current sources		
C) input section as voltage source and output section as current source		
D) input section as current source and output section as voltage source	F	-
40. n-parameters are used for the low frequency analysis of BJT amplifier analysis because	L]
A) n parameters are real numbers up to radio frequencies D) they are easy to measure		
D) they are easy to measure		
C) readily supplied by manufacturers D) all of the above		
<i>D</i>) an of the above		

<u>UNIT V</u> FIELD EFFECT TRANSISTOR

1. The JFET is []
A) a bipolar device B) unipolar device C) voltage controlled device D) both (B) and (C))
2. The channel of a JFET exists between []
A) gate and source B) drain and source C) gate and drain D) None of the above	
3. For low values of V _{DS} , the JFET behaves like a []
A) resistance B) constant voltage device C) constant current device D) None	
4. In an N channel JFET [RRB-JE-2012] []
A) the current carriers are holes B) the current carriers are electrons	
C) V _{GS} is positive D) the input resistance is very low	
5. In a P channel JFET []
A) the current carriers are electrons B) the current carriers are holes	
C) V _{GS} is negative D) the input resistance is very small	
6. For an N channel JFET (GATE 1990) []
A) V_{GS} can vary between zero negatively to V_{GSO} B) V_{GS} can vary between zero positively t	o V _{GSO}
C) pinch off occurs for positive V_{GS} D) V_{DD} is negative	
7. An FET cannot operate at $V_{GS} = 0V$. The FET is []
A) JFET B) D-MOSFET C) E-MOSFET D) None of the above	
8. The transconductance g_m of JFET is defined as []
A) I_D / V_{GS} B) I_D / V_{DS} C) V_{GS} / I_D D) I_{DSS} / I_D	
9. The amplification factor μ of JFET is given by [IES-2010] []
A) $\mu = g_m / r_d$ B) $g_m = \mu * r_d$ C) $\mu = g_m * r_d$ D) $r_d = g_m - \mu$	
10. The drain resistance r _d is given by []
A) $\mu * g_m$ B) I_D / V_{DS} C) V_{DS} / I_D D) none of the above	
11. Ideally, the equivalent circuit of an FET consists of [GATE 2017]]
A) a resistance between drain and source	
B) a current source between the gate and the source	
C) a current source between the drain and the source	
D) none of the above	
12. The magnitude of the current source in the ac equivalent circuit of an FET depends on	
A) the dc supply voltage B) V_{DS} C) externally drain resistance C) none of the above	
13. Which one of the following has the highest input resistance?	
A) NPN transistor in CB configuration B) PNP transistor in CE configuration	
C) N type channel JFET D) P type channel MOSFET	
14. The current conduction of JFET involved	
A) a flow of minority carriers B) a flow of majority carriers	
C) Recombination D) none of the above	
15. The JFET is also called as	
A) voltage controlled device B) current controlled device C) bipolar device D) none	
16. Which of the following statements is true? [GATE 2014]	
A) FET and BJT, both are unipolar B) FET and BJT, both are bipolar	
C) FET is bipolar and BJT is unipolar D) FET is unipolar and BJT is bipolar	·
17. An FET has a	
A) very high input resistance B) very low input resistance	
C) high connection emitter junction D) none of the above	· 1
18. For small values of drain to source voltage, JFE1 behaves like a	.]
A) resistor B) constant current source C) constant voltage source D) none of the above	· 1
19. In a JFE1, the primary control on drain current is exerted by	
A) channel resistance B) size of depletion regions C) gate reverse bias D) none of the at 20 . After V merchanism is a first large V is a IEET the during argument because	pove
20. After v_{DS} reaches plinch off voltage v_P in a JFE1, the drain current becomes [J
A) ZEIO B) saturated C) IOW D) none of the above	
21. The Drain Characteristics curve of a JFE1 is a graph of:	J
A) IS VEISUS V DS D) IC VEISUS V CE C) ID VEISUS V DS D) ID VEISUS V GS 22 In a IEEE drain aurrant is maximum when $V_{\rm ce}$ is ICATE 200(1)	
22. In a JTET, than current is maximum when v_{GS} is [GATE 2000] [A) zero B) negative C) positive D) none of the above	
A_{j} ΔA_{j} ΔA_{j} A_{j}	

23. A JFET has input impedance when compared to BJT.	[]
A) low B) high C) zero D) none of the above		
24. The drain to source voltage at which the drain current becomes nearly constant is call	led []
A) barrier voltage B) breakdown voltage C) high voltage D) pin	choff voltag	ge
25. The Transfer Characteristics curve of a JFET is a graph of:	[
A) I _S versus V_{DS} B) I _C versus V_{CE} C) I _D versus V_{DS} D) I _D versus V	√GS	-
26. The depletion MOSFET differs from a JFET in the sense that it has no	[1
A) channel B) gate C) PN junctions D) substrate	Ľ	-
27. For the operation of enhancement n-channel MOSFET, the gate voltage will be [IES]	2014] [1
A) high positive B) high negative C) low positive D) zero		-
28. The gate terminal of JFET corresponds to terminal of BJT.	1	1
A) collector B) base C) emitter D) none of the above	L	1
29. The main factor which differentiates depletion MOSEET from an enhancement only		
MOSFET is the absence of [GATE 2009]	ſ	1
A) insulated gate B) electrons C) channel D) PN Junctic	on	L
30 The phase shift between input and output of common source amplifier is]	1
A) 0^0 B) 180^0 C) 90^0 D) none of the above	L	Ţ
31 In a FET amplifier the source follower is	ſ	1
A) CS amplifier B) CG amplifier C) CD amplifier D) none of the above	L	1
32 The voltage controls the drain current flow in FFT is	ſ	1
A) V_{CS} B) V_{DS} C) V_{CC} D) none of the above	L	1
33 The gate source voltage of a IEET should be $[CATE 2008]$	г	1
A) forward biased B) reverse biased C) unbiased D) none of the above	L	1
34 The input impedance of an ideal IEET is	г	1
A impossible to predict B approaches to unity C approaches to infinity D po	l na of tha ah	
35 The charge carriers in an N channel IEET are		1
A) about range $B)$ holds $C)$ neutrons $D)$ none of the above	L	1
26 The seturation region of IEET is also known as	r	1
So. The saturation region of $JTET$ is also known as A) Dirich off \mathbf{P}) analog C source \mathbf{D}) Obmin	L]
A) Finch on B) analog C source D) Onnic	г	1
A) only deplotion mode D) only enhancement mode C) both deplotion and only	L	D) mama
A) only depiction mode B) only emiancement mode C) both depiction and em	r iancement	D) none
38. when a JFET is pinched off, the depiction layers are	L]
A) conducting B) close together C) Far apart D) none of the above	г	1
39. The insulated Gate Field Effect Transistor is [GATE 2009]	L]
A) MOSFEI B) JFEI C) BJI D) none of the above		1
40. when a JFET is cut off, its like a switch and when its saturated its like	switch.]
A) closed, closed B) open, closed C) open, open D) none of the above		

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